

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Georg Meyer-Berg</td> <td>11/17/2004</td> </tr> <tr> <td>Barbara Vasquez</td> <td>12/22/2004</td> </tr> </tbody> </table>		Name	Execution Date	Georg Meyer-Berg	11/17/2004	Barbara Vasquez	12/22/2004
Name	Execution Date						
Georg Meyer-Berg	11/17/2004						
Barbara Vasquez	12/22/2004						
RECEIVING PARTY DATA							
Name:	Infineon Technologies AG						
Street Address:	St. Martin Str. 53						
City:	Munich						
State/Country:	GERMANY						
Postal Code:	81669						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10960994</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10960994		
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Application Number:	10960994						
CORRESPONDENCE DATA							
Fax Number:	(301)762-4056						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	3014243640						
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Correspondent Name:	Edell, Shapiro & Finnan LLC						
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NAME OF SUBMITTER:	Heather Morin						
Total Attachments: 2 source=Assignment1#page1.tif source=Assignment1#page2.tif							

OP \$40.00 10960994

ASSIGNMENT

For good and valuable consideration, WE, Georg Meyer-Berg, a citizen of Germany, residing at Hofangerstr. 71A, 81735 München, Germany, and Barbara Vasquez, a citizen of the United States of America, residing at 1100 Via Media, Lafayette, California 94549, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on _____ US. Serial No. _____,

entitled: **Electronic Component Having at Least One Semiconductor Chip and Flip-Chip Contacts, and Method for Producing the Same**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____

Georg Meyer-Berg
Georg Meyer-Berg

DATE: _____

2004-11-17

SIGNATURE: _____

Barbara Vasquez

DATE: _____

ASSIGNMENT

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SIGNATURE: _____ DATE: _____
Georg Meyer-Berg

SIGNATURE: Barbara Vasquez _____ DATE: 12/22/04 *BW*
Barbara Vasquez